

### 384 OUTPUT TFT-LCD SOURCE DRIVER (COMPATIBLE WITH 64 GRAY SCALES)

The  $\mu$ PD16637 is a source driver for TFT-LCDs capable of dealing with displays with 64 gray scales. Data input is based on digital input configured as 6 bits by 6 dots (2 pixels), which can realize a full-color display of 260,000 colors by output of 64 values  $\gamma$ -corrected by an internal D/A converter and 5-by-2 external power modules. Because the output dynamic range is as large as 12.3 V<sub>P-P</sub>, level inversion operation of the LCD's common electrode is rendered unnecessary. Also, to be able to deal with dot-line inversion when mounted on a single side, this source driver is equipped with a built-in 6-bit D/A converter circuit whose odd output pins and even output pins respectively output gray scale voltages of differing polarity. Assuring a maximum clock frequency of 55 MHz when driving at 3.0 V, this driver is applicable to XGA-standard TFT-LCD panels.

#### FEATURES

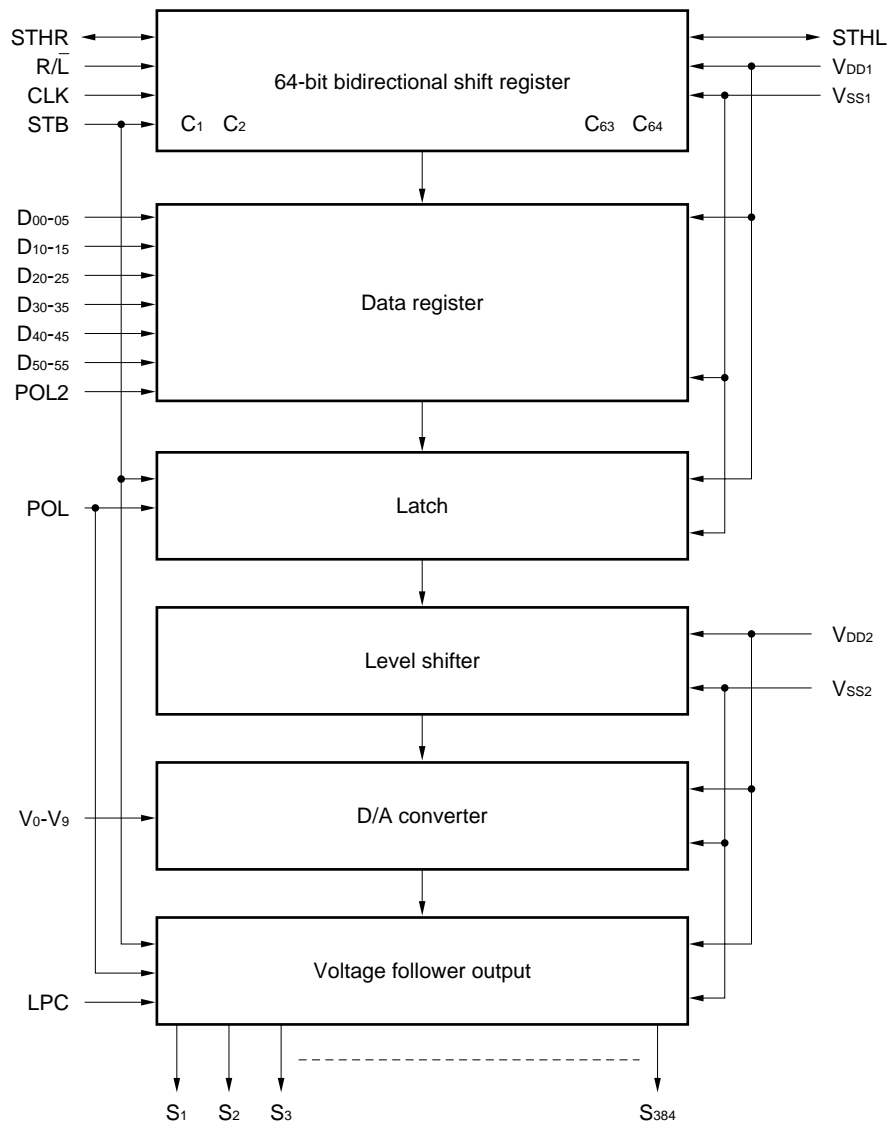
- Capable of outputting 64 values by means of 5-by-2 external power modules (10 units) and a D/A converter
- Output dynamic range 12.3 V<sub>P-P</sub> min. (@ V<sub>DD2</sub> = 12.5 V)
- Power supply voltage of driver part = V<sub>DD2</sub> = 13.0  $\pm$ 0.5 V
- CMOS level input
- Input of 6 bits (gradation data) by 6 dots
- High-speed data transfer: f<sub>max.</sub> = 55 MHz (internal data transfer speed when operating at 3.0 V)
- Display data inversion function (POL2 terminal.)
- 384 outputs
- Single bank arrangement is possible (loaded with slim TCP)

#### ORDERING INFORMATION

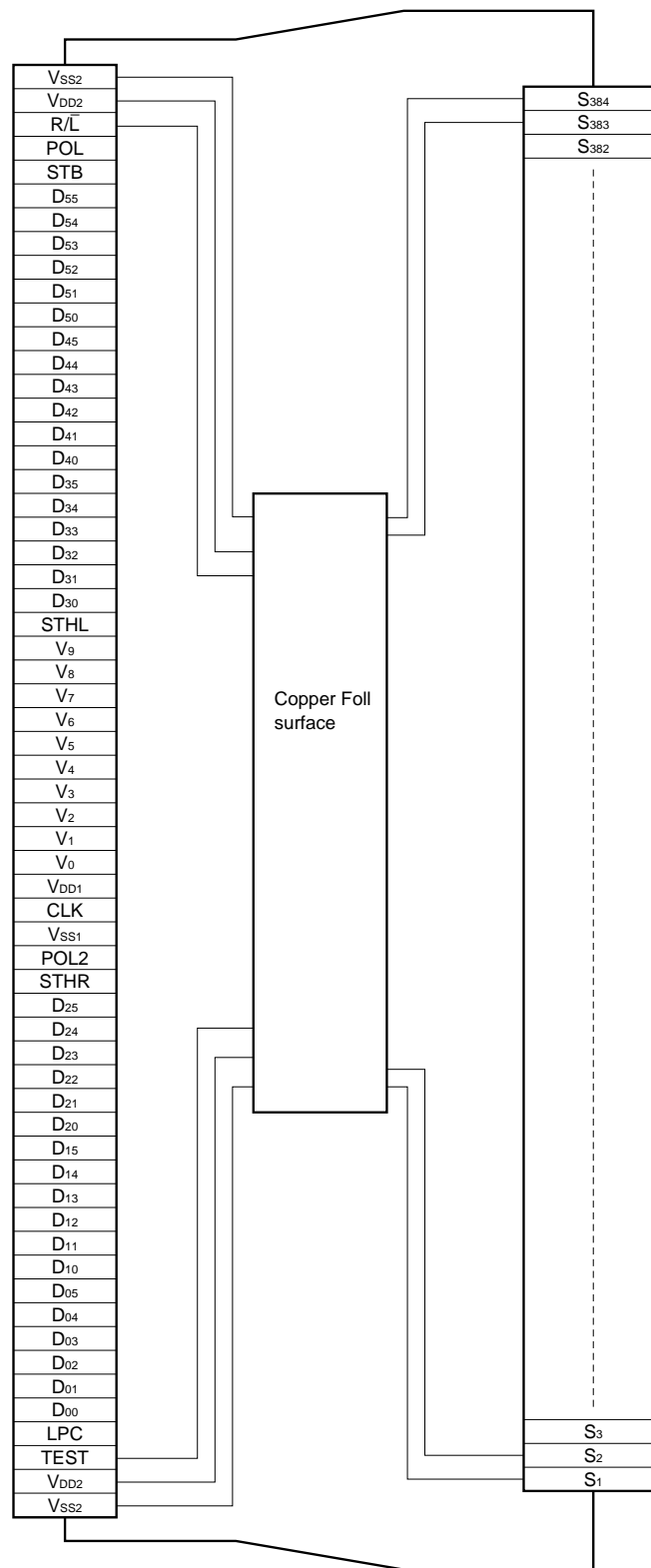
Part Number	Package
$\mu$ PD16637N-xxx	TCP (TAB package)

The TCP's external shape is customized. To order your TCP's external shape, please contact an NEC salesperson.

1. BLOCK DIAGRAM

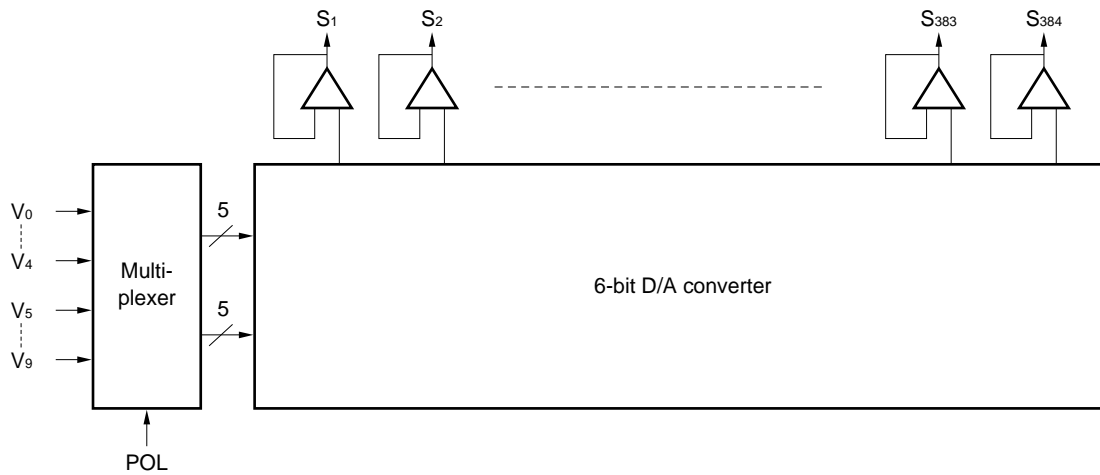


2. PIN CONFIGURATION (μPD16637N-xxx)



**Remark** This figure does not specify the TCP package.  
 It is possible to reduce a number of input lead by wiring POL2 terminal to V<sub>SS2</sub> on TCP if data inversion function is not necessary.

3. RELATIONSHIP BETWEEN OUTPUT CIRCUIT AND D/A CONVERTER



POL	$S_{2n-1}$	$S_{2n}$
L	$V_0$ to $V_4$	$V_5$ to $V_9$
H	$V_5$ to $V_9$	$V_0$ to $V_4$

$S_{2n-1}$  (odd output),  $S_{2n}$  (even output)  $n = 1, 2, \dots, 192$

4. PIN FUNCTIONS

Pin Symbol	Pin Name	Description
S <sub>1</sub> to S <sub>384</sub>	Driver output	The D/A converted 64-gray-scale analog voltage is output.
D <sub>01</sub> to D <sub>05</sub>	Display data input	The display data is input with a width of 36 bits, viz., the gray scale data (6 bits) by 6 dots (2 pixels). D <sub>x0</sub> : LSB, D <sub>x5</sub> : MSB
D <sub>10</sub> to D <sub>15</sub>		
D <sub>20</sub> to D <sub>25</sub>		
D <sub>31</sub> to D <sub>35</sub>		
D <sub>40</sub> to D <sub>45</sub>		
D <sub>50</sub> to D <sub>55</sub>		
R $\bar{L}$	Shift direction switching input	These refer to the start pulse input/output pins when cascades are connected. The shift direction of the shift registers are as follows. R $\bar{L}$ = H : STHR input, S <sub>1</sub> → S <sub>384</sub> , STHL output R $\bar{L}$ = L : STHL input, S <sub>384</sub> → S <sub>1</sub> , STHR output
STHR	Right shift start pulse input/output	R $\bar{L}$ = H : Becomes the start pulse input pin. R $\bar{L}$ = L : Becomes the start pulse output pin.
STHL	Left shift start pulse input/output	R $\bar{L}$ = H : Becomes the start pulse input pin. R $\bar{L}$ = L : Becomes the start pulse output pin.
CLK	Shift clock input	Refers to the shift register's shift clock input. The display data is incorporated into the data register at the rising edge. At the rising edge of the 64th clock after the start pulse input, the start pulse output reaches the high level, thus becoming the start pulse of the next-level driver. The initial-level driver's 64th clock becomes valid as the next-level driver's start pulse is input. If 66 clock pulses are input after input of the start pulse, input of display data is halted automatically. The contents of the shift register are cleared at the STB's rising edge.
STB	Latch input	The contents of the data register are transferred to the latch at the rising edge. And, at the falling edge, the gray scale voltage is supplied to the driver. It is necessary to ensure input of one pulse per horizontal period.
LPC	Low power control input	The output buffer constant current source is blocked, reducing current consumption. In lower power mode (LPC = 'H': DC-level input possible), the ordinary static current consumption can be reduced by approx. 50 %. The condition that low power mode can be used is that the load constant is at least 5 kΩ + 100 pF.
POL	Polarity input	POL = L ; The S <sub>2n-1</sub> output uses V <sub>5</sub> to V <sub>9</sub> as the reference supply; and the S <sub>2n</sub> output uses V <sub>0</sub> to V <sub>4</sub> as the reference supply. POL = H; The S <sub>2n-1</sub> output uses V <sub>0</sub> to V <sub>4</sub> as the reference supply; and the S <sub>2n</sub> output uses V <sub>5</sub> to V <sub>9</sub> as the reference supply.
POL2	Data inversion	POL2 = H : Display data is inverted. POL2 = L : Display data is not inverted.
V <sub>0</sub> to V <sub>9</sub>	γ-corrected power supplies	Input the γ-corrected power supplies from outside. Make sure to maintain the following relationships. During the gray scale voltage output, be sure to keep the gray scale level power supply at a constant level. V <sub>DD2</sub> > V <sub>0</sub> > V <sub>1</sub> > V <sub>2</sub> > V <sub>3</sub> > V <sub>4</sub> > V <sub>5</sub> > V <sub>6</sub> > V <sub>7</sub> > V <sub>8</sub> > V <sub>9</sub> > V <sub>SS</sub>
TEST	Test pin	Set it to 'OPEN'.
V <sub>DD1</sub>	Logic power supply	3.3 V ±0.3 V
V <sub>DD2</sub>	Driver power supply	13.0 V ±13.5 V
V <sub>SS1</sub>	Logic ground	Grounding
V <sub>SS2</sub>	Driver ground	Grounding

- Cautions**
1. The power start sequence must be  $V_{DD1}$ , logic input, and  $V_{DD2}$  &  $V_0$  to  $V_9$  in that order. Reverse this sequence to shut down. (Simultaneous power application to  $V_{DD2}$  and  $V_0$  to  $V_9$  is possible.)
  2. To stabilize the supply voltage, please be sure to insert a  $0.47 \mu\text{F}$  bypass capacitor between  $-V_{DD1}-V_{SS1}$  and  $V_{DD2}-V_{SS2}$ . Furthermore, for increased precision of the D/A converter, insertion of a bypass capacitor of about  $0.01 \mu\text{F}$  is also advised between the  $\gamma$ -corrected power supply terminals ( $V_0, V_1, V_2, \dots, V_9$ ) and  $V_{SS2}$ .

5. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT VOLTAGE VALUE

This product incorporates a 6-bit D/A converter whose odd output pins and even output pins output respectively gray scale voltages of differing polarity with respect to the LCD's counter electrode (common electrode) voltage. The D/A converter consists of ladder resistors and switches. The ladder resistors  $r_0$  to  $r_{62}$  are so designed that the ratios between the LCD panel's  $\gamma$ -corrected voltages and  $V_{0'}$  to  $V_{63'}$  and  $V_{0''}$  to  $V_{63''}$  are roughly equal; and their respective resistance values are as shown on page 9. Among the 5-by-2  $\gamma$ -corrected voltages, input gray scale voltages of the same polarity with respect to the common voltage, for the respective five  $\gamma$ -corrected voltages of  $V_0$  to  $V_4$  and  $V_5$  to  $V_9$ . If fine gray scale voltage precision is not necessary, the voltage follower circuit supplied to the  $\gamma$ -corrected power supplies  $V_1$  to  $V_3$  and  $V_6$  to  $V_8$  can be deleted.

Figure 1 shows the relationship between the driving voltages such as liquid-crystal driving voltages  $V_{DD2}$  and  $V_{SS2}$ , common electrode potential  $V_{COM}$ , and  $\gamma$ -corrected voltages  $V_0$  to  $V_9$  and the input data. Be sure to maintain the voltage relationships of  $V_{DD2} > V_0 > V_1 > V_2 > V_3 > V_4 > V_5 > V_6 > V_7 > V_8 > V_9 > V_{SS2}$ . Figures 2-1 and 2-2 show the relationship between the input data and the output data. Table 1 shows the resistance values of the resistor strings.

This driver IC is designed for single-sided mounting. Therefore, please do not use it for  $\gamma$ -corrected power supply level inversion in double-sided mounting.

Because the current flowing through ladder resistors  $r_0$  to  $r_{62}$  is small, its use for double-sided mounting impairs the IC's stable operation when the level of the  $\gamma$ -corrected power supply terminal is inverted thus causing display failures.

Figure 1. Relationship Between Input Data and Output Voltage

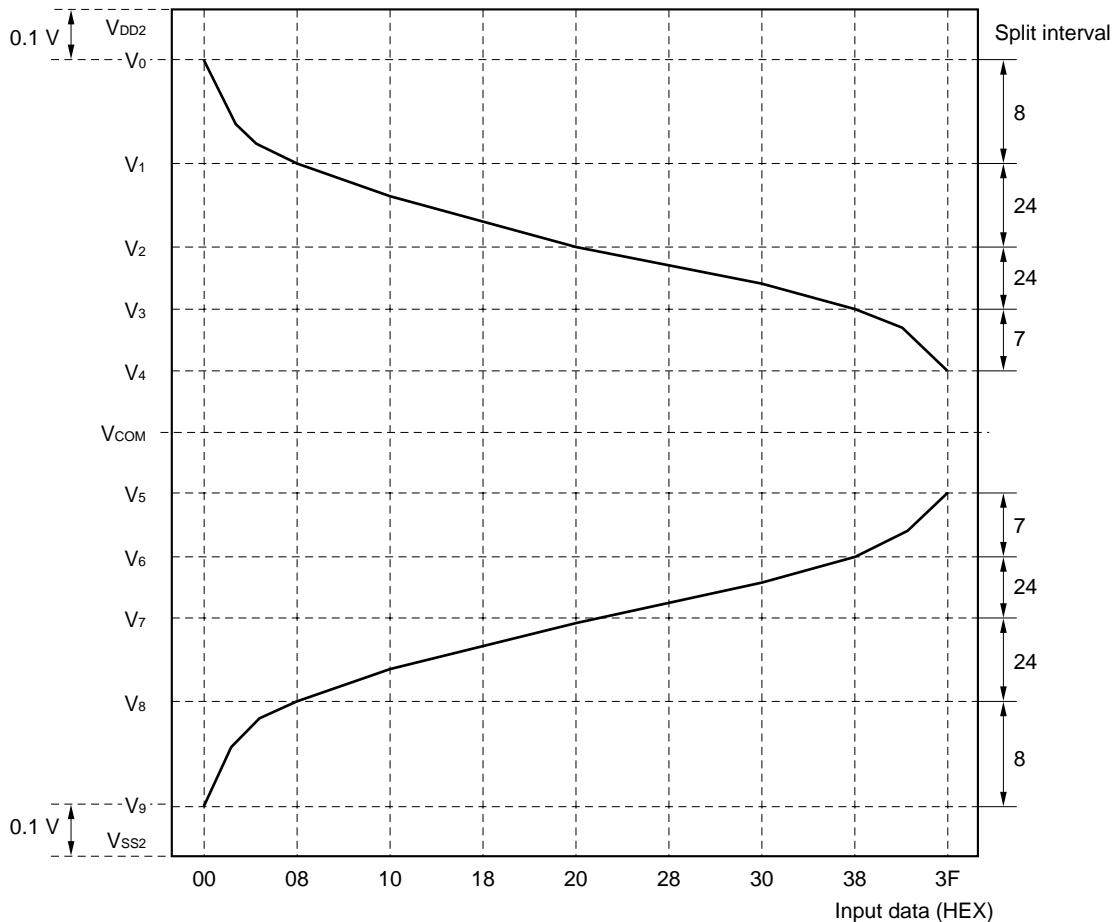
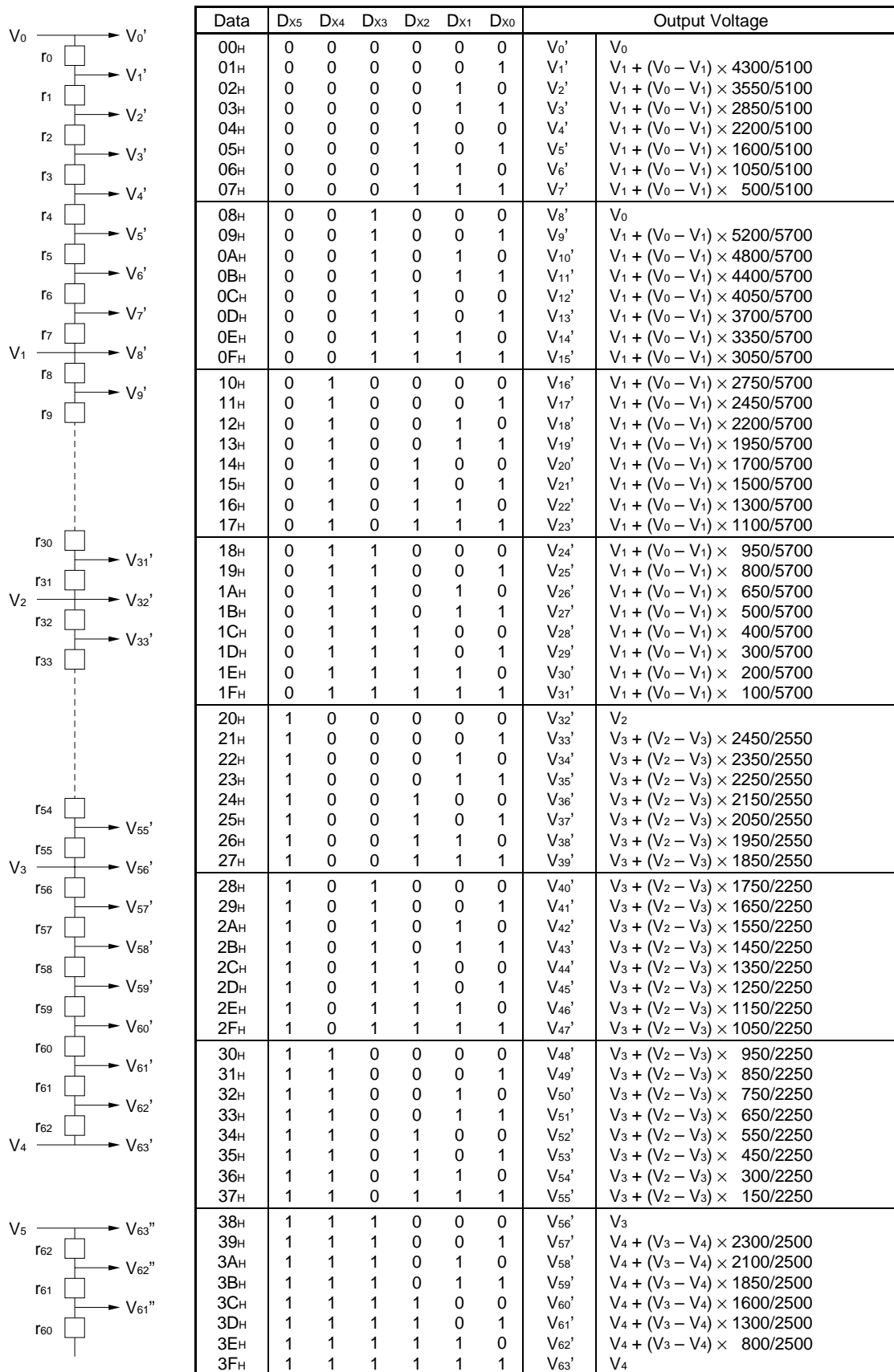


Figure 2-1. Relationship Between Input Data and Output Voltage:  $V_{DD2} > V_0 > V_1 > V_2 > V_3 > V_4 > V_5$







**Table 1. Resistance values of the resistor strings**

	Resistor Name	Resistance Value (Ω)	Resistor Name	Resistance Value (Ω)	
V <sub>0</sub> , V <sub>9</sub> →	r <sub>0</sub>	800	r <sub>32</sub>	100	← V <sub>2</sub> , V <sub>7</sub>
	r <sub>1</sub>	750	r <sub>33</sub>	100	
	r <sub>2</sub>	700	r <sub>34</sub>	100	
	r <sub>3</sub>	650	r <sub>35</sub>	100	
	r <sub>4</sub>	600	r <sub>36</sub>	100	
	r <sub>5</sub>	550	r <sub>37</sub>	100	
	r <sub>6</sub>	550	r <sub>38</sub>	100	
V <sub>1</sub> , V <sub>8</sub> →	r <sub>7</sub>	500	r <sub>39</sub>	100	
	r <sub>8</sub>	500	r <sub>40</sub>	100	
	r <sub>9</sub>	400	r <sub>41</sub>	100	
	r <sub>10</sub>	400	r <sub>42</sub>	100	
	r <sub>11</sub>	350	r <sub>43</sub>	100	
	r <sub>12</sub>	350	r <sub>44</sub>	100	
	r <sub>13</sub>	350	r <sub>45</sub>	100	
	r <sub>14</sub>	300	r <sub>46</sub>	100	
	r <sub>15</sub>	300	r <sub>47</sub>	100	
	r <sub>16</sub>	300	r <sub>48</sub>	100	
	r <sub>17</sub>	250	r <sub>49</sub>	100	
	r <sub>18</sub>	250	r <sub>50</sub>	100	
	r <sub>19</sub>	250	r <sub>51</sub>	190	
	r <sub>20</sub>	200	r <sub>52</sub>	100	
	r <sub>21</sub>	200	r <sub>53</sub>	150	
	r <sub>22</sub>	200	r <sub>54</sub>	150	
	r <sub>23</sub>	150	r <sub>55</sub>	150	← V <sub>3</sub> , V <sub>6</sub>
	r <sub>24</sub>	150	r <sub>56</sub>	200	
	r <sub>25</sub>	150	r <sub>57</sub>	200	
	r <sub>26</sub>	150	r <sub>58</sub>	250	
	r <sub>27</sub>	100	r <sub>59</sub>	250	
	r <sub>28</sub>	100	r <sub>60</sub>	300	
	r <sub>29</sub>	100	r <sub>61</sub>	500	
	r <sub>30</sub>	100	r <sub>62</sub>	800	← V <sub>4</sub> , V <sub>5</sub>
V <sub>2</sub> , V <sub>7</sub> →	r <sub>31</sub>	100	Total	15850	

6. RELATIONSHIP BETWEEN INPUT DATA AND OUTPUT PIN

Data format: 6 bits × 2 RGBs (6 dots)

Input width : 36 bits (2-pixel data)

$\overline{R/L} = H$  (Right shift)

Output	S <sub>1</sub>	S <sub>2</sub>	S <sub>3</sub>	S <sub>4</sub>	S <sub>5</sub>	...	S <sub>383</sub>	S <sub>384</sub>
Data	D <sub>00</sub> to D <sub>05</sub>	D <sub>10</sub> to D <sub>15</sub>	D <sub>20</sub> to D <sub>25</sub>	D <sub>30</sub> to D <sub>35</sub>	D <sub>40</sub> to D <sub>45</sub>	...	D <sub>40</sub> to D <sub>45</sub>	D <sub>50</sub> to D <sub>55</sub>

$\overline{R/L} = L$  (Left shift)

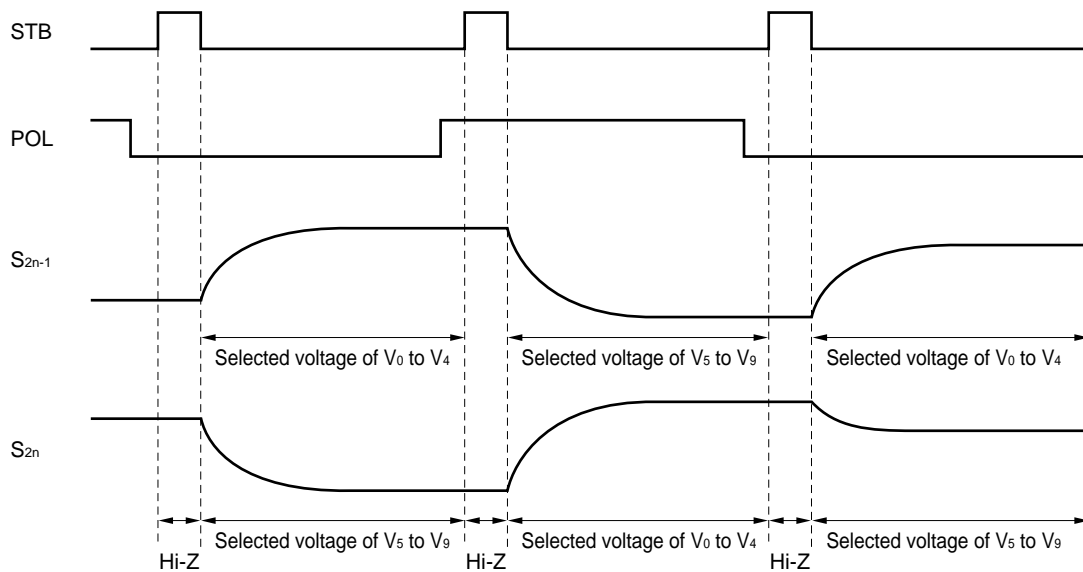
Output	S <sub>1</sub>	S <sub>2</sub>	S <sub>3</sub>	S <sub>4</sub>	S <sub>5</sub>	...	S <sub>383</sub>	S <sub>384</sub>
Data	D <sub>00</sub> to D <sub>05</sub>	D <sub>10</sub> to D <sub>15</sub>	D <sub>20</sub> to D <sub>25</sub>	D <sub>30</sub> to D <sub>35</sub>	D <sub>40</sub> to D <sub>45</sub>	...	D <sub>40</sub> to D <sub>45</sub>	D <sub>50</sub> to D <sub>55</sub>

POL	S <sub>2n-1</sub>	S <sub>2n</sub>
L	V <sub>0</sub> to V <sub>4</sub>	V <sub>5</sub> to V <sub>9</sub>
H	V <sub>5</sub> to V <sub>9</sub>	V <sub>0</sub> to V <sub>4</sub>

S<sub>2n-1</sub> (Odd output), S<sub>2n</sub> (Even output) n = 1, 2, ..., 192

7. RELATIONSHIP BETWEEN STB, POL, AND OUTPUT WAVEFORM

The output voltage is written to the LCD panel synchronized with the STB rising edge.



8. CAUTION OF OPERATION

μPD16637 is full dot inversion driver with change charge buffer for discharge buffer on every other horizontal line. Since the output polarity of last line on a frame can not be same with the output polarity of first line on a next frame (Figure 3), necessary to polarity change and output operation in the interval of two frames (Figure 4).

Figure 3.

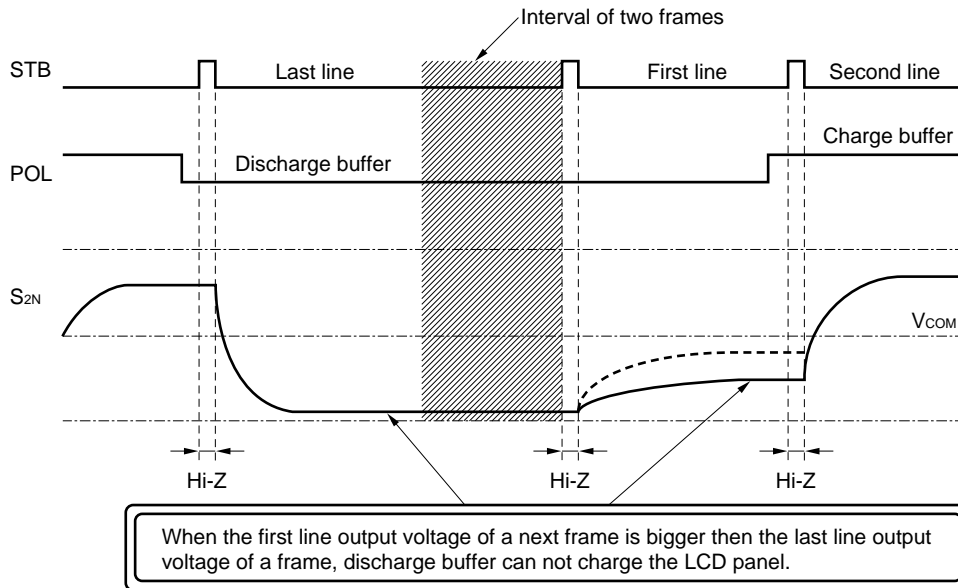
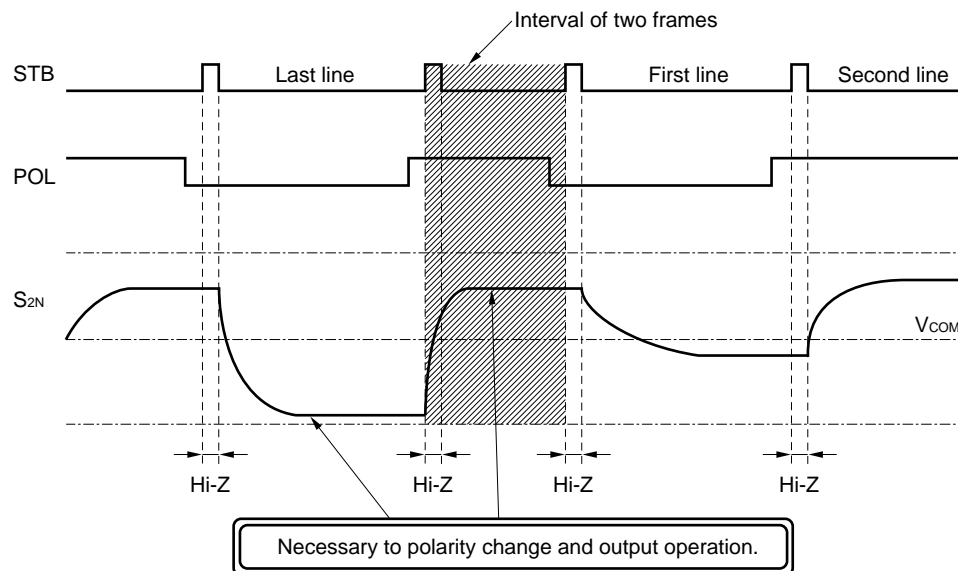


Figure 4.



9. ELECTRIC SPECIFICATION

Absolute Maximum Ratings (T<sub>A</sub> = 25°C, V<sub>SS1</sub> = V<sub>SS2</sub> = 0 V)

Parameter	Symbol	Rating	Unit
Logic Part Supply Voltage	V <sub>DD1</sub>	-0.5 to +6.5	V
Driver Part Supply Voltage	V <sub>DD2</sub>	-0.5 to +15.0	V
Logic Part Input Voltage	V <sub>I1</sub>	-0.5 to V <sub>DD1</sub> +0.5	V
Driver Part Input Voltage	V <sub>I2</sub>	-0.5 to V <sub>DD2</sub> +0.5	V
Logic Part Output Voltage	V <sub>O1</sub>	-0.5 to V <sub>DD1</sub> +0.5	V
Driver Part Output Voltage	V <sub>O2</sub>	-0.5 to V <sub>DD2</sub> +0.5	V
Operating Temperature Range	T <sub>A</sub>	-10 to +75	°C
Storage Temperature Range	T <sub>stg.</sub>	-55 to +125	°C

Recommended Operating Range (T<sub>A</sub> = -10 to +75°C, V<sub>SS1</sub> = V<sub>SS2</sub> = 0 V)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Logic Part Supply Voltage	V <sub>DD1</sub>	3.0	3.3	3.6	V
Driver Part Supply Voltage	V <sub>DD2</sub>	12.5	13.0	13.5	V
High-Level Input Voltage	V <sub>IH</sub>	0.7 V <sub>DD1</sub>		V <sub>DD1</sub>	V
Low-Level Input Voltage	V <sub>IL</sub>	0		0.3 V <sub>DD1</sub>	V
γ-Corrected Voltage	V <sub>0</sub> to V <sub>9</sub>	V <sub>SS2</sub> + 0.1		V <sub>DD2</sub> - 0.1	V
Driver Part Output Voltage	V <sub>O</sub>	V <sub>SS2</sub> + 0.1		V <sub>DD2</sub> - 0.1	V
Maximum Clock Frequency	f <sub>max.</sub>	55			MHz

Electrical Specifications (T<sub>A</sub> = -10 to +75°C, V<sub>DD1</sub> = 3.3 V ±0.3 V, V<sub>DD2</sub> = 13.0 V ±0.5 V, V<sub>SS1</sub> = V<sub>SS2</sub> = 0 V)

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Input Leak Current	I <sub>L</sub>				±1.0	μA
High-Level Output Voltage	V <sub>OH</sub>	STHR (STHL), I <sub>o</sub> = 0 mA	V <sub>DD1</sub> - 0.1			V
Low-Level Output Voltage	V <sub>OL</sub>	STHR (STHL), I <sub>o</sub> = 0 mA			0.1	V
γ-Corrected Supply Current	I <sub>Vn</sub>	V <sub>DD2</sub> = 13.0 V	V <sub>0</sub> , V <sub>5</sub>	0.4	0.8	mA
		V <sub>0</sub> - V <sub>4</sub> = V <sub>5</sub> - V <sub>9</sub> = 6 V	V <sub>4</sub> , V <sub>9</sub>	-0.4	-0.8	mA
Driver Output Current	V <sub>VOH</sub>	V <sub>X</sub> = 10 V, V <sub>OUT</sub> = 1 V <sup>Note</sup>			-3.0	mA
	V <sub>VOL</sub>	V <sub>X</sub> = 1 V, V <sub>OUT</sub> = 10 V <sup>Note</sup>	3.0			mA

**Note** V<sub>X</sub> refers to the output voltage of analog output pins S<sub>1</sub> to S<sub>384</sub>.

V<sub>OUT</sub> refers to the voltage applied to analog output pins S<sub>1</sub> to S<sub>384</sub>.

**Electrical Specifications (T<sub>A</sub> = -10 to +75°C, V<sub>DD1</sub> = 3.3 V ±0.3 V, V<sub>DD2</sub> = 13.0 V ±0.5 V, V<sub>SS1</sub> = V<sub>SS2</sub> = 0 V)**

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Output Voltage Deviation <sup>Note 1</sup>	ΔV <sub>O</sub>	Input data: 00 <sub>H</sub> to 3F <sub>H</sub>		±8	±20	mV
Average Output Voltage Variation <sup>Note 2</sup>	ΔV <sub>AV</sub>	Input data: 00 <sub>H</sub> to 3F <sub>H</sub>		±11		mV
Output Voltage Range	V <sub>O</sub>	Input data: 00 <sub>H</sub> to 3F <sub>H</sub>	0.1		V <sub>DD2</sub> - 0.1	V
Logic Part Dynamic Current Consumption	I <sub>DD1</sub>	V <sub>DD1</sub> ; when with no load <sup>Notes 3, 4</sup>		3.3	9.0	mA
Driver Part Dynamic Current Consumption	I <sub>DD22</sub>	V <sub>DD2</sub> ; when with no load <sup>Notes 3, 4</sup>		14.9	30.0	mA

- Notes 1.** The output voltage deviation refers to the voltage difference between adjoining output pins when the display data is the same (within the chip).
- 2.** The average output voltage variation refers to the average output voltage difference between chips. The average output voltage refers to the average voltage between chips when the display data is the same.
- 3.** The STB cycle is defined to be 16.6 μs at f<sub>CLK</sub> = 40 MHz. The TYP. values refer to an all black or all white input pattern. The MAX. value refers to the measured values in the dot checkerboard input pattern.
- 4.** Refers to the current consumption per driver when cascades are connected under the assumption of XGA single-sided mounting (8 units).

**Switching Characteristics (T<sub>A</sub> = -10 to +75°C, V<sub>DD1</sub> = 3.3 V ±0.3 V, V<sub>DD2</sub> = 13.0 V ±0.5 V, V<sub>SS1</sub> = V<sub>SS2</sub> = 0 V)**

Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Start Pulse Delay Time	t <sub>PLH1</sub>	C <sub>L</sub> = 25 pF		9.7	12	ns
Driver Output Delay Time 1	t <sub>PHL2</sub>	C <sub>L</sub> = 200 pF, R <sub>L</sub> = 5 kΩ		2.0	8	μs
Driver Output Delay Time 2	t <sub>PHL3</sub>	C <sub>L</sub> = 200 pF, R <sub>L</sub> = 5 kΩ		2.8	12	μs
Driver Output Delay Time 3	t <sub>PLH2</sub>	C <sub>L</sub> = 200 pF, R <sub>L</sub> = 5 kΩ		2.1	8	μs
Driver Output Delay Time 4	t <sub>PLH3</sub>	C <sub>L</sub> = 200 pF, R <sub>L</sub> = 5 kΩ		2.7	12	μs
Input Capacitance 1	C <sub>1</sub>	STHR, STHL excluded T <sub>A</sub> = 25°C		9.8	15	pF
Input Capacitance 2	C <sub>2</sub>	STHR, STHL T <sub>A</sub> = 25°C		8.5	15	pF

**Timing Requirement**

( $T_A = -10$  to  $+75^\circ\text{C}$ ,  $V_{DD1} = 3.3\text{ V} \pm 0.3\text{ V}$ ,  $V_{SS1} = V_{SS2} = 0\text{ V}$ ,  $t_r = t_f = 8.0\text{ ns}$ )

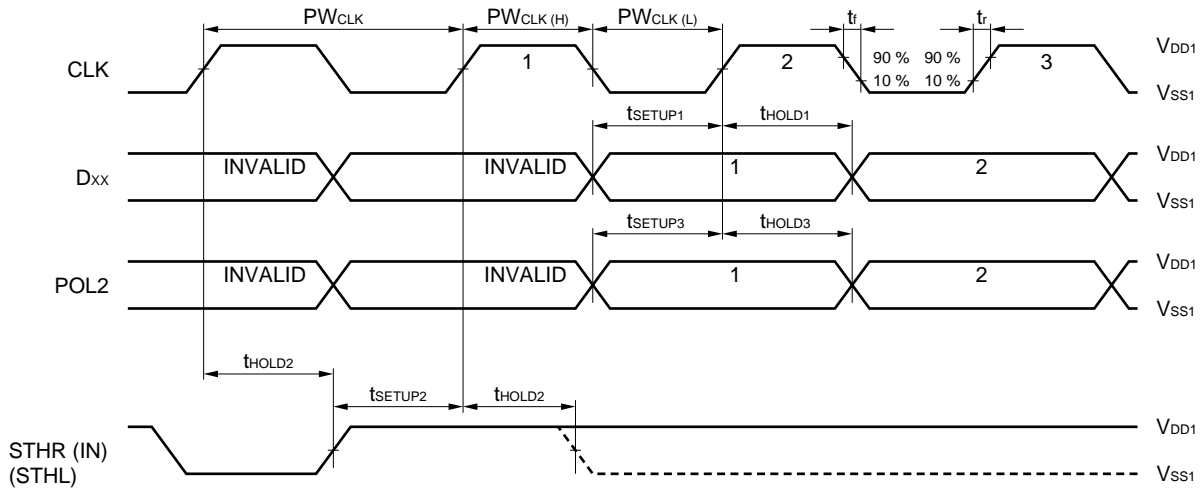
Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Clock Pulse Width	$PW_{CLK}$		18			ns
Clock Pulse Low Period	$PW_{CLK(L)}$		4			ns
Clock Pulse High Period	$PW_{CLK(H)}$		4			ns
Data Setup Time	$t_{SETUP1}$		3			ns
Data Hold Time	$t_{HOLD1}$		3			ns
Start Pulse Setup Time	$t_{SETUP2}$		5			ns
Start Pulse Hold Time	$t_{HOLD2}$		5			ns
POL2 Setup Time	$t_{SETUP3}$		4			ns
POL2 Hold Time	$t_{HOLD3}$		4			ns
Start Pulse Low Period	$t_{SPL}$		5			ns
STB Pulse Width	$PW_{STB}$		0.5			μs
Data Invalid Period	$t_{INV}$		1			CLK
Final Data Timing	$t_{LDT}$		2			CLK
CLK-STB Time	$t_{CLK-STB}$	CLK ↑ → STB ↓	5			ns
STB-CLK Time	$t_{STB-CLK}$	STB ↓ → CLK ↑	5			ns
Time Between STB and Start Pulse	$t_{STB-STH}$	STB ↓ → STHR ↑	50			ns
POL-STB Time	$t_{POL-STB}$	POL ↑ or ↓ → STB ↑	-5			ns
STB-POL Time	$t_{STB-POL}$	STB ↓ → POL ↓ or ↑	5			ns

10. SWITCHING CHARACTERISTICS WAVEFORM (R/L = H)

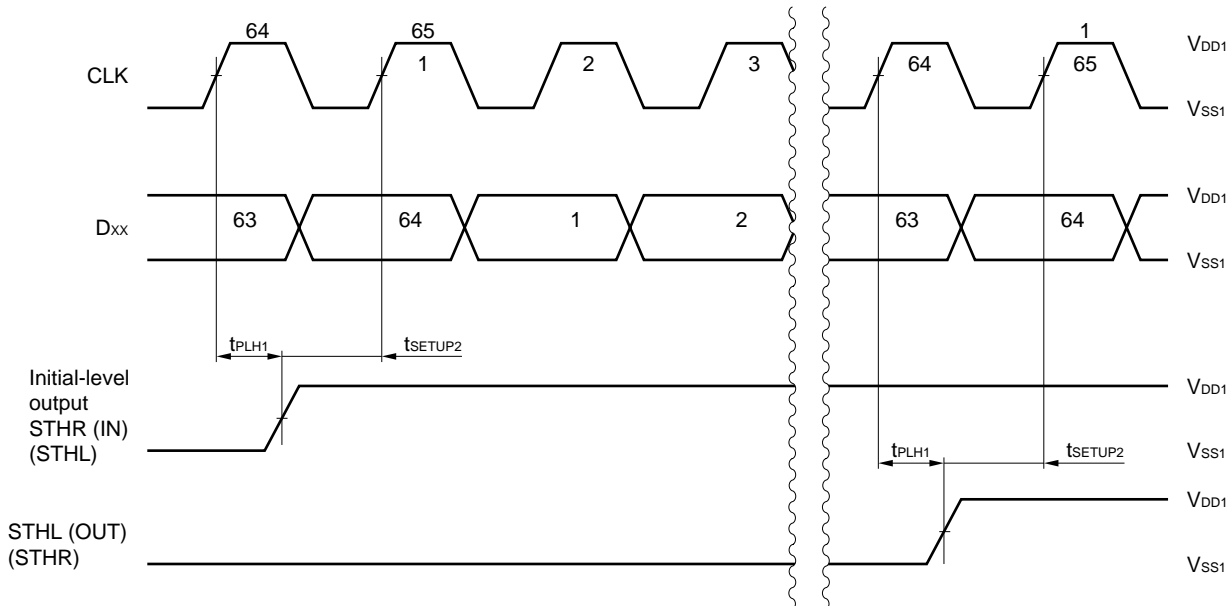
In ( ): R/L = L

Unless otherwise specified, the input level is defined to be 0.5 V<sub>DD1</sub>.

(1) Initial-Stage Driver's Input/Output Waveform

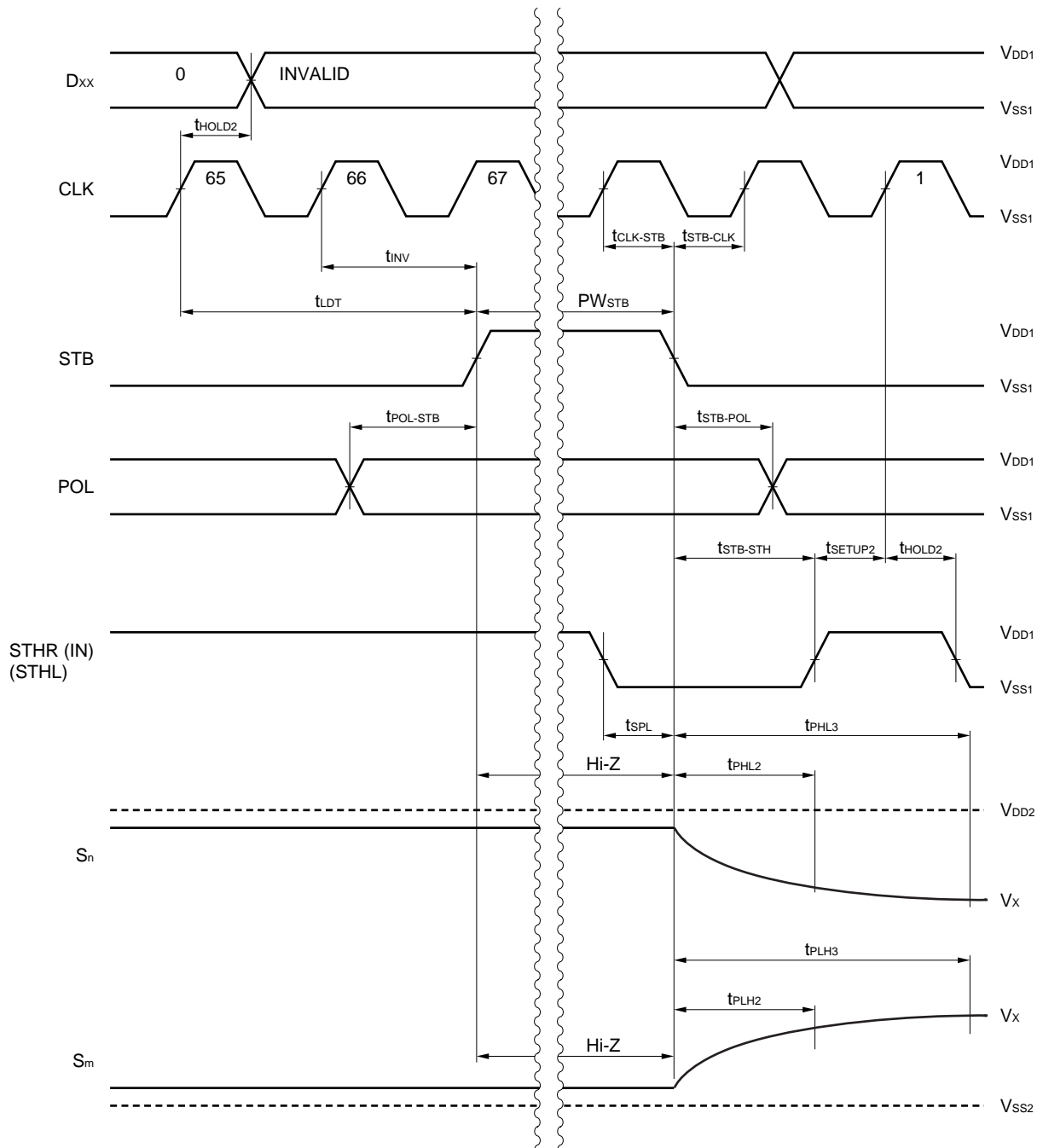


(2) Second- to Final-Stage Driver's Input/Output Timing





(3) Driver Output Timing



$V_x$  refers to the final output voltage.  $t_{PHL2}$  and  $t_{PHL2}$  refer to the time required to reach an output precision level of 10% ( $0.1 V_x$ ); and  $t_{PLH3}$  and  $t_{PHL3}$  refer to the time required to reach an output precision level of 6 bits.

**11. RECOMMENDED MOUNTING CONDITIONS**

When mounting this product, please make sure that the following recommended conditions are satisfied.

For packaging methods and conditions other than those recommended below, please contact NEC sales personnel.

Mounting Condition	Mounting Method	Condition
Thermocompression	Soldering	Heating tool 300 to 350°C; heating for 2 to 3 seconds; pressure 100 g (per solder)
	ACF (Adhesive Conductive Film)	Temporary bonding 70 to 100°C; pressure 3 to 8 kg/cm <sup>2</sup> ; time 3 to 5 secs. Real bonding 165 to 180°C; pressure 25 to 45 kg/cm <sup>2</sup> ; time 30 to 40 secs. (When using the anisotropic conductive film SUMIZAC1003 of Sumitomo Bakelite, Ltd.)

**Caution To find out the detailed conditions for packaging the ACF part, please contact the ACF manufacturing company. Be sure to avoid using two or more packaging methods at a time.**

**REFERENCE**

NEC Semiconductor Device Reliability/Quality Control System (C10983E)

Quality Grades to NEC's Semiconductor Devices (C11531E)

[MEMO]

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Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots

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Specific: Aircrafts, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

The quality grade of NEC devices is "Standard" unless otherwise specified in NEC's Data Sheets or Data Books. If customers intend to use NEC devices for applications other than those specified for Standard quality grade, they should contact an NEC sales representative in advance.

Anti-radioactive design is not implemented in this product.